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(12) **United States Design Patent**
Miyamoto et al.

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(54) **CIRCUIT MODULE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

Jan. 20, 2006 (JP) 2006-001051

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/119,
D13/182; 320/134; 361/103; 429/7, 61,
429/90, 123

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a circuit module, as shown.

DESCRIPTION

FIG. 1 is a perspective view of the top, front and right side of a circuit module showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

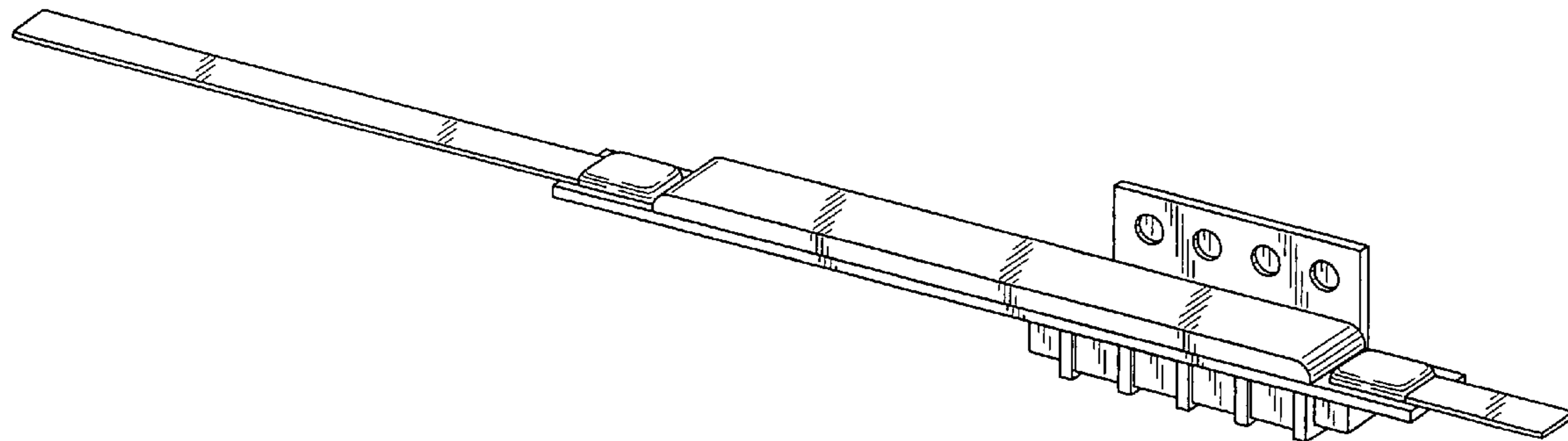
FIG. 4 is a left side elevational view thereof;

FIG. 5 is a right side elevational view thereof;

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

1 Claim, 3 Drawing Sheets



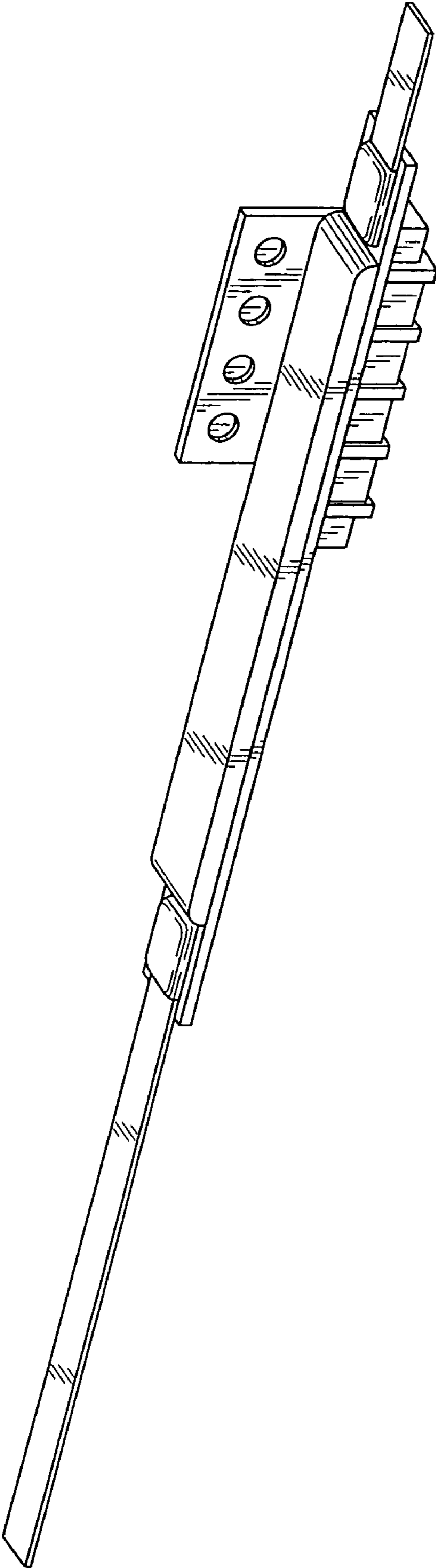


FIG. 1

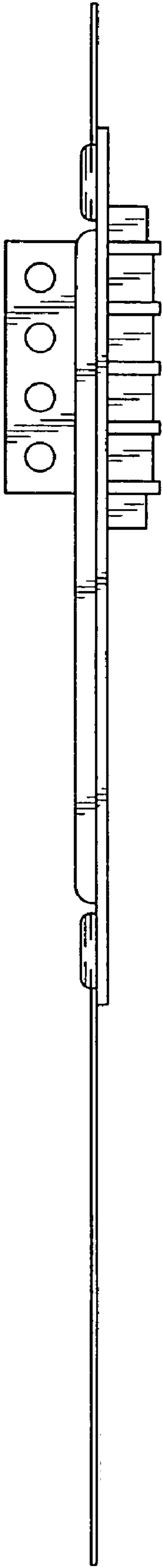


FIG. 2

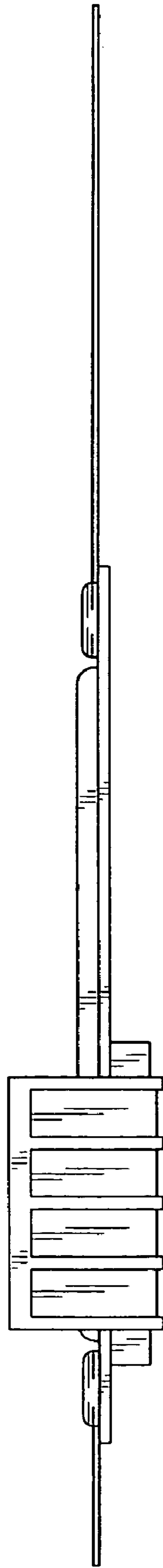


FIG. 3

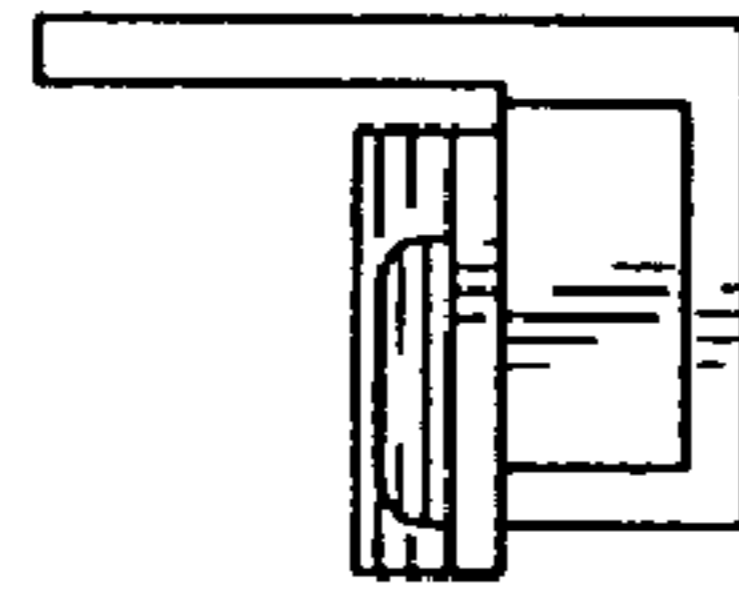


FIG. 5

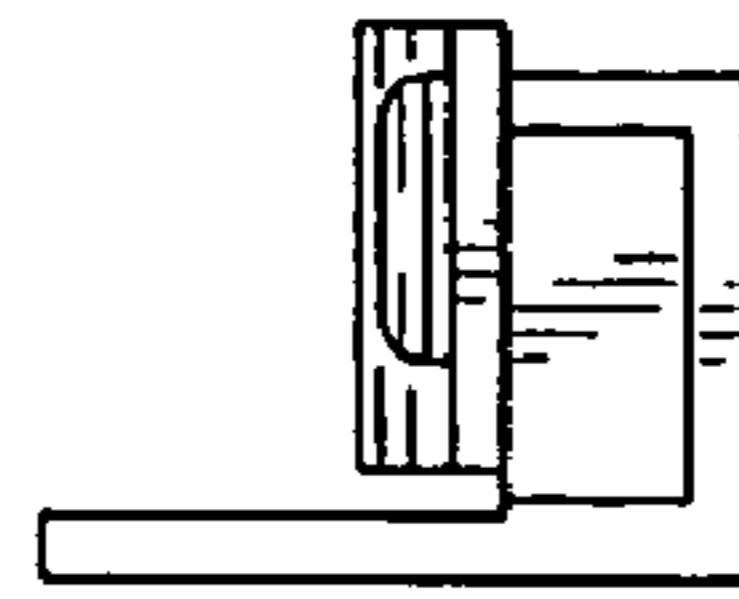


FIG. 4

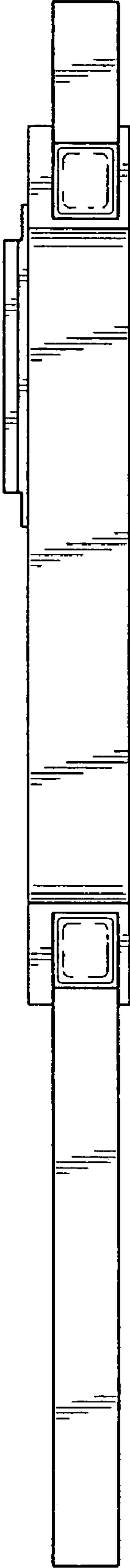


FIG. 6

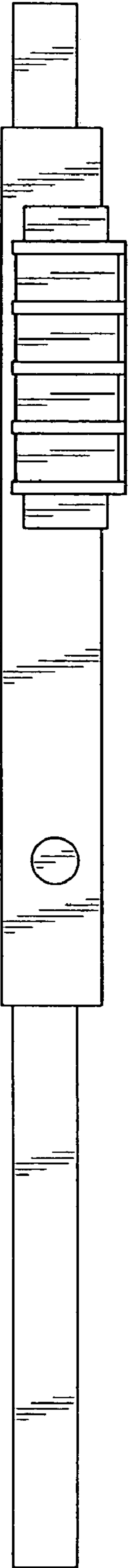


FIG. 7